

Spectroscopic EUV reflectometry for characterization of thin film systems and determination of optical constants

Maksym Tryus, Serhiy Danylyuk, Larissa Juschkin

RWTH Aachen University

Konstantin Nikolaev, Igor Makhotkin

University of Twente

Daniel Wilson, Lidia Kibkalo, Jürgen Schubert

Forschungszentrum Jülich

Angelo Giglia, Piergiorgio Nicolosi

Istituto Officina Materiali Trieste, Universita' degli Studi di Padova



Motivation

Why EUV reflectometry?

Innovative surface sensitive metrology with EUV radiation

alternative to existing
(non-destructive) metrology tools

need for „at wavelength“
characterization of EUV optics

Potential:

- ultra-thin film analysis (**any material**)
- determination of chemical bonds at surfaces
(**near edge absorption fine structure**)
- surface sensitive technique (**penetration depth ~ 10-100 nm**)
- surface roughness determination
(**smooth surface limit beyond VIS or UV**)
- high spatial resolution (**$\ll 1 \mu\text{m}$**)
- defect inspection (**„nano“roughness** in terms of spatial-frequency)

- at **synchrotron** reflectometers
- **laboratory based** reflectometers

*Long-term goal:
transfer techniques into the lab*

simultaneous acquisition from one measurement

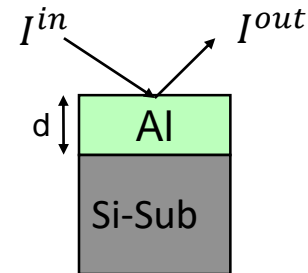
➤ **experimental determination of EUV optical constants**

Angle-resolved vs. spectral reflectometry

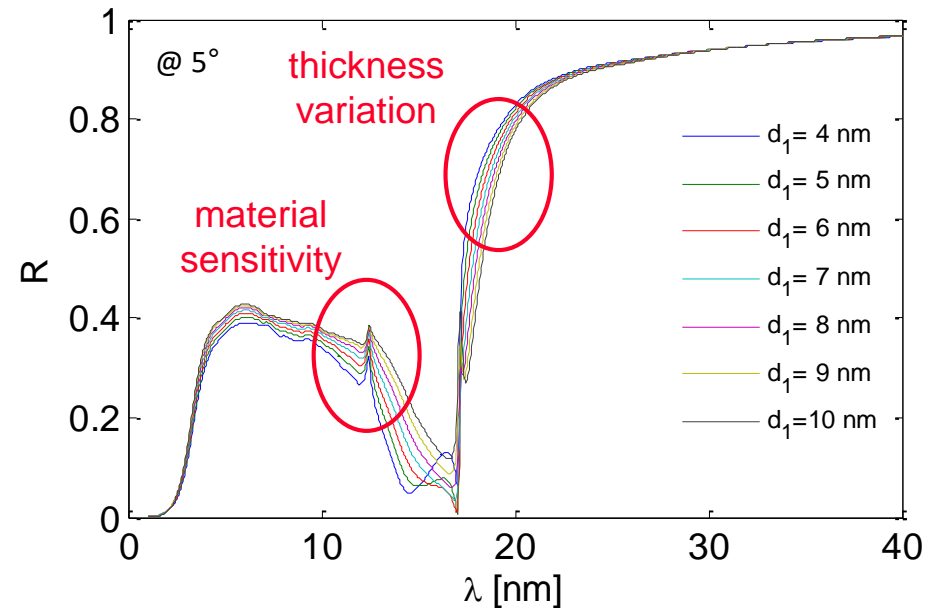
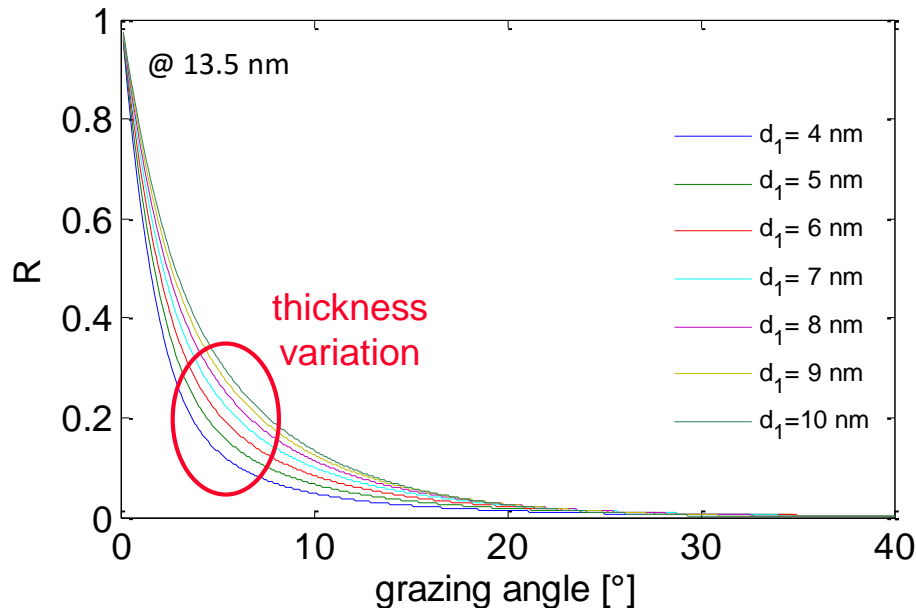
Layer parameters determination:

(by fitting experimental data with a model)

- Thickness
- Density
- Roughness



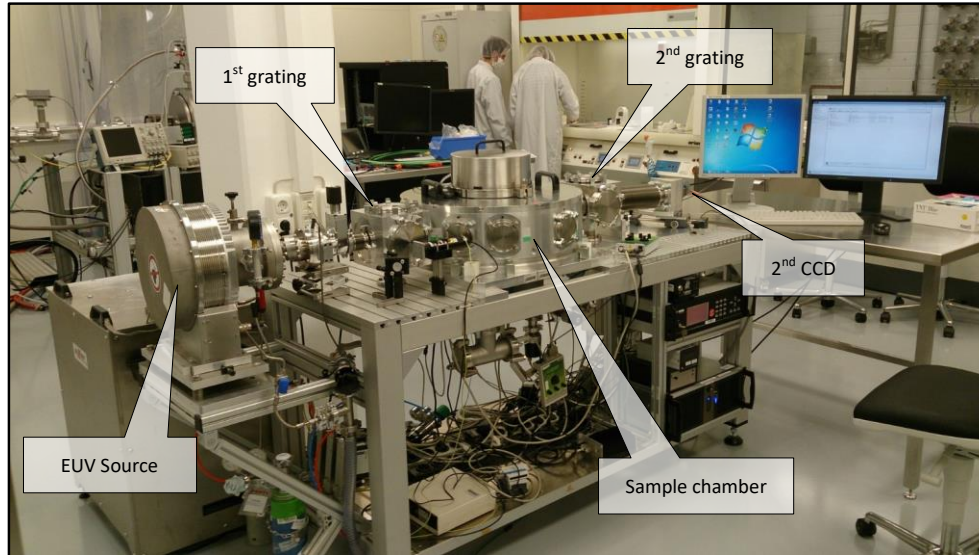
$$R(\theta, \lambda) = I^{out} / I^{in}$$



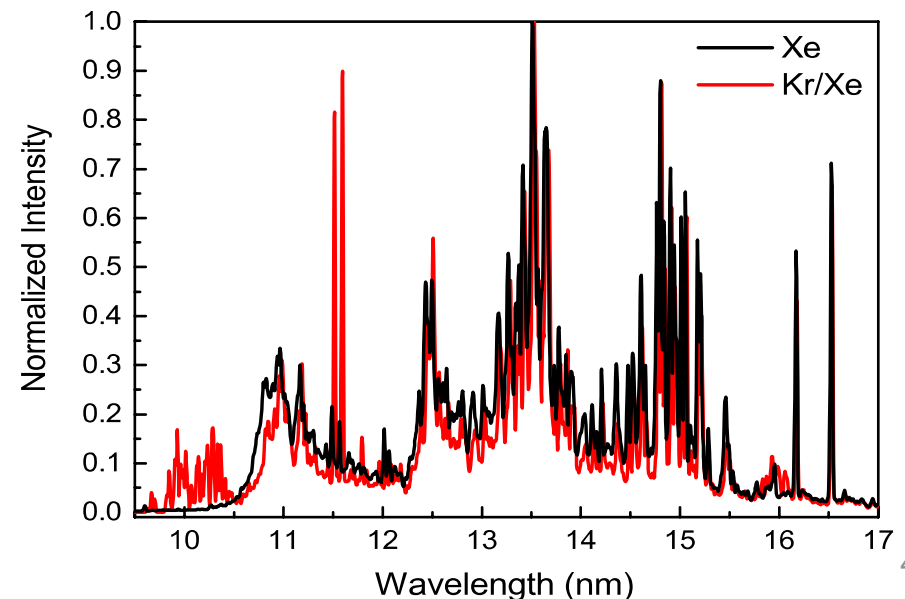
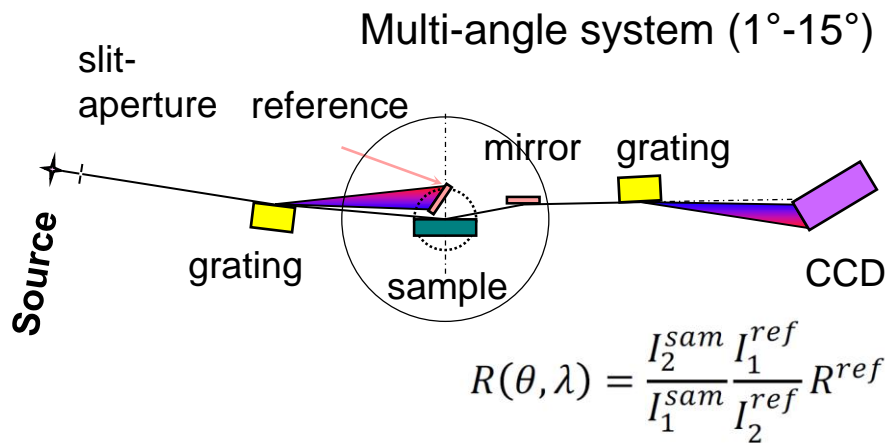
➤ Absorption edges: elemental & chemical sensitivity

➤ Total external reflection at high critical angles
(up to 10° – 20°)

Polychromatic Angle-resolving Non-destructive Tool for High-speed Extreme-ultraviolet Reflectometry – PANTHER



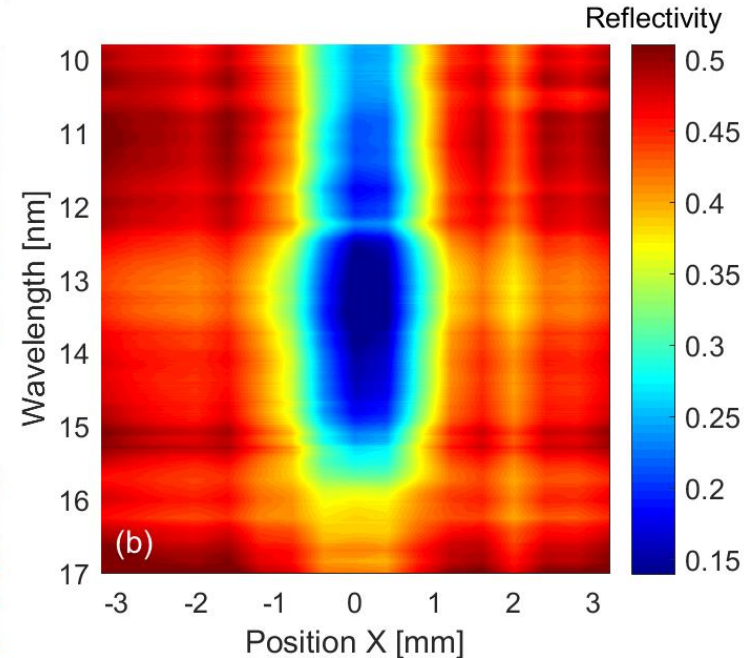
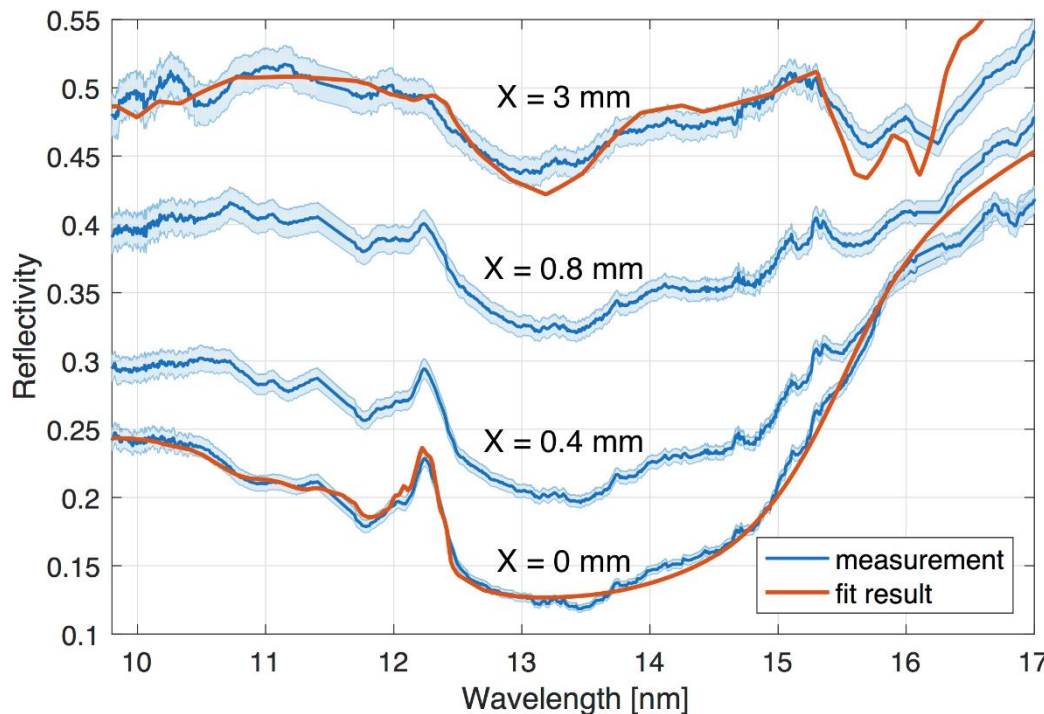
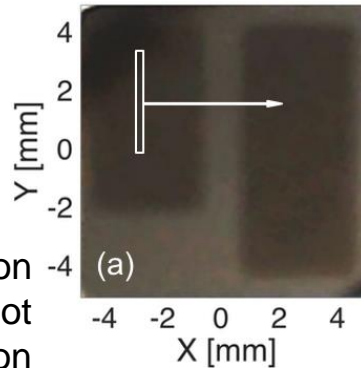
- Wavelength range: 9 - 17 nm
- Spectral resolution: 5 pm
- Incidence angles: 1 - 15°
- Angular resolution: 0.005°
- Pulse-to-pulse measurements
- Pulse duration: 10 - 100 ns
- Thickness sensitivity: ~0.1 nm
- Sample size <100 mm



Spatially resolved spectroscopic EUV reflectometry

Application example:
study of collector optics
contamination due its
proximity to EUV source

Si sample with contamination
regions with marked EUV spot
footprint and scan direction



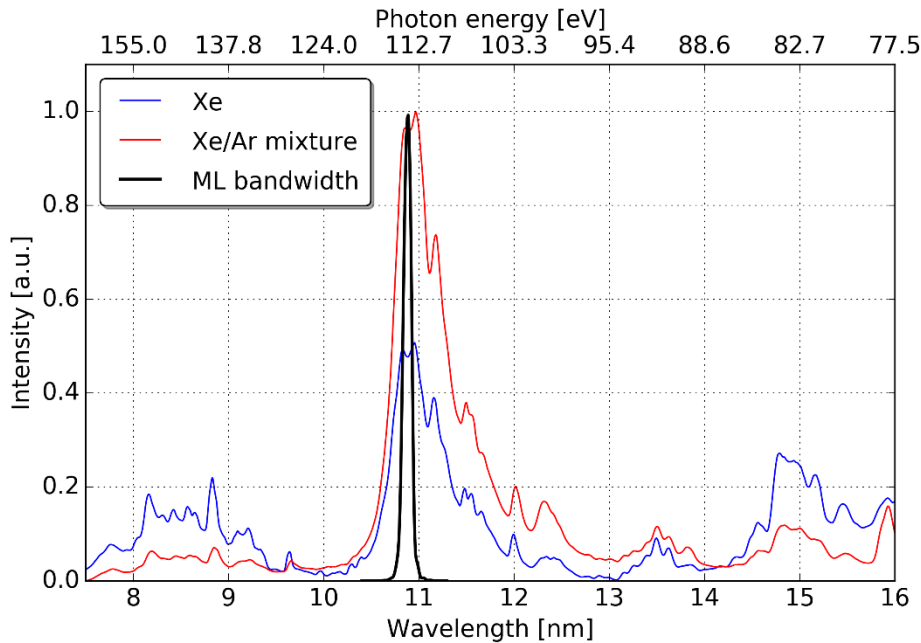
Resulting spectral reflectivity map

Reflectivity spectra (blue) & fit results (red)
at different sample positions

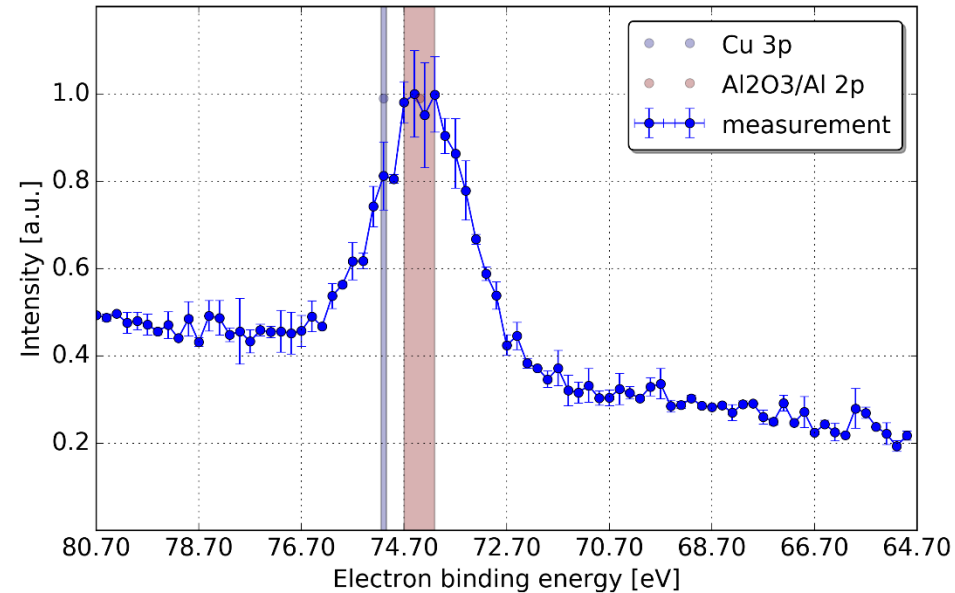
Non-contaminated part (X = 0 mm)
shows presence of natural silicon
oxide layer (4 nm) and non-uniform
rough layer of carbon (2.5 nm) on top.

Contaminated region (X = 3 mm) has
0.7 nm carbon and 10 nm amorphous
 Al_2O_3 topping oxidized silicon wafer.

Cross-correlation with photoemission electron microscopy (PEEM)



EUV emission spectra utilized for PEEM:
 $\lambda = 10.9 \text{ nm}$ ($E_{\text{photon}} = 113.7 \text{ eV}$) was filtered by two narrow-bandwidth multilayer mirrors with $\Delta\lambda = 0.1 \text{ nm}$



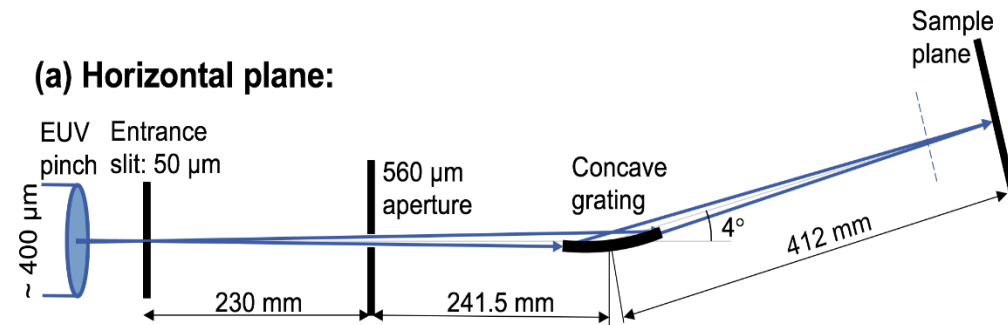
Section of photoelectron spectrum measured at 113.7 eV photon energy with highlighted electron binding energies of materials that fit within the peak

- From PEEM results, one cannot clearly distinguish between oxidized aluminum and copper
- EUV reflectometry clearly shows presence of aluminum oxide, ruling out the copper content, which also fits to the sample history
- Carbon contamination could not be tested with PEEM, as used photon energy of 113.7 eV was lower than the electron binding energy of the carbon K-shell

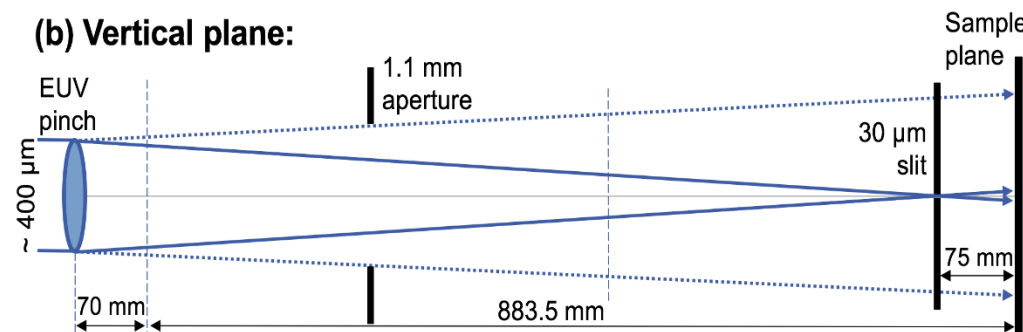
Spatial resolution of the PANTHER

Sample illumination scheme of reflectometer with 30 μm slit in front of sample plane (dotted line: beam path without this slit)

(a) Horizontal plane:



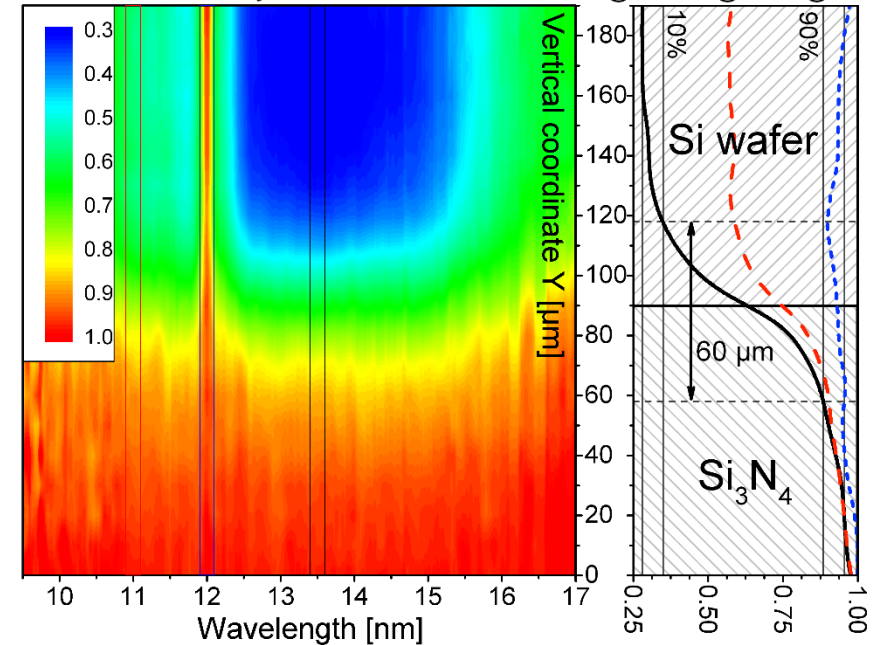
(b) Vertical plane:



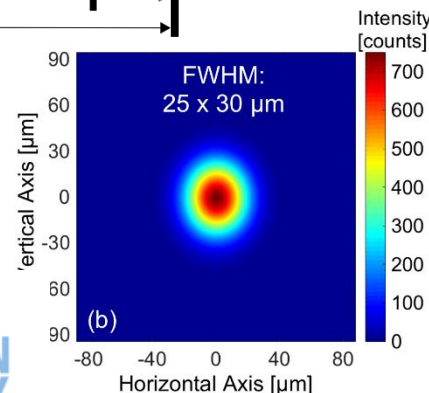
Ultimate illumination spot size
(at sample: $25 \mu\text{m}/\sin\theta \times 30 \mu\text{m}$)

For smaller spots imaging optics needed

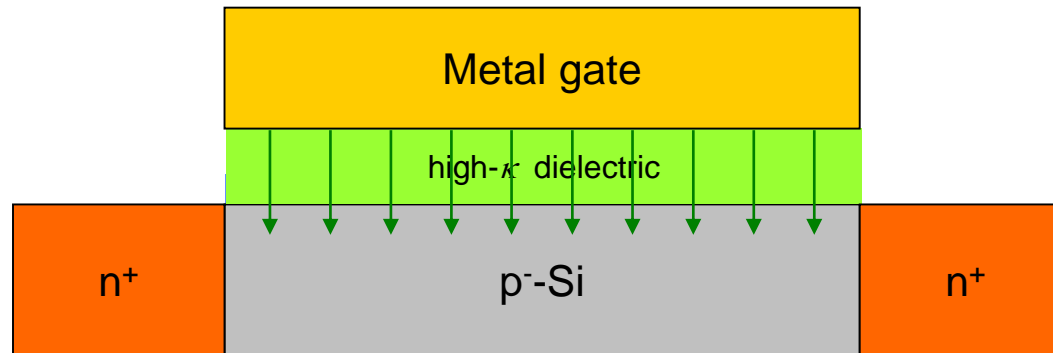
Relative reflectivity



Relative reflectivity scan at 8° grazing incidence across an abrupt horizontal Si/Si₃N₄ field border with vertical sample movement; reflectivity profiles at 11, 12, and 13.5 nm; knife-edge resolution test at 13.5 nm



Application example: high- κ dielectrics



$$C = \kappa \frac{\epsilon_0 A}{d}$$

C: capacitance

A: area of capacitor

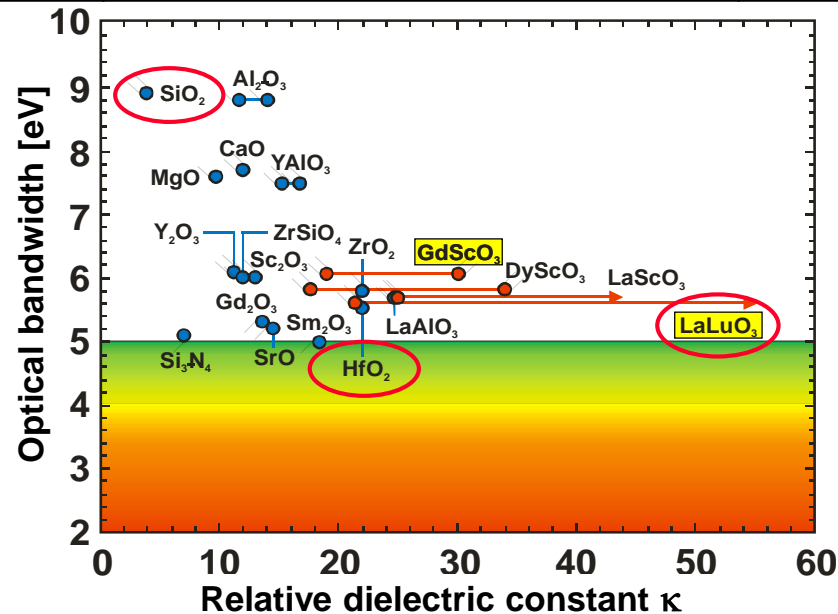
d: thickness of insulator

ϵ_0 : permittivity of free space

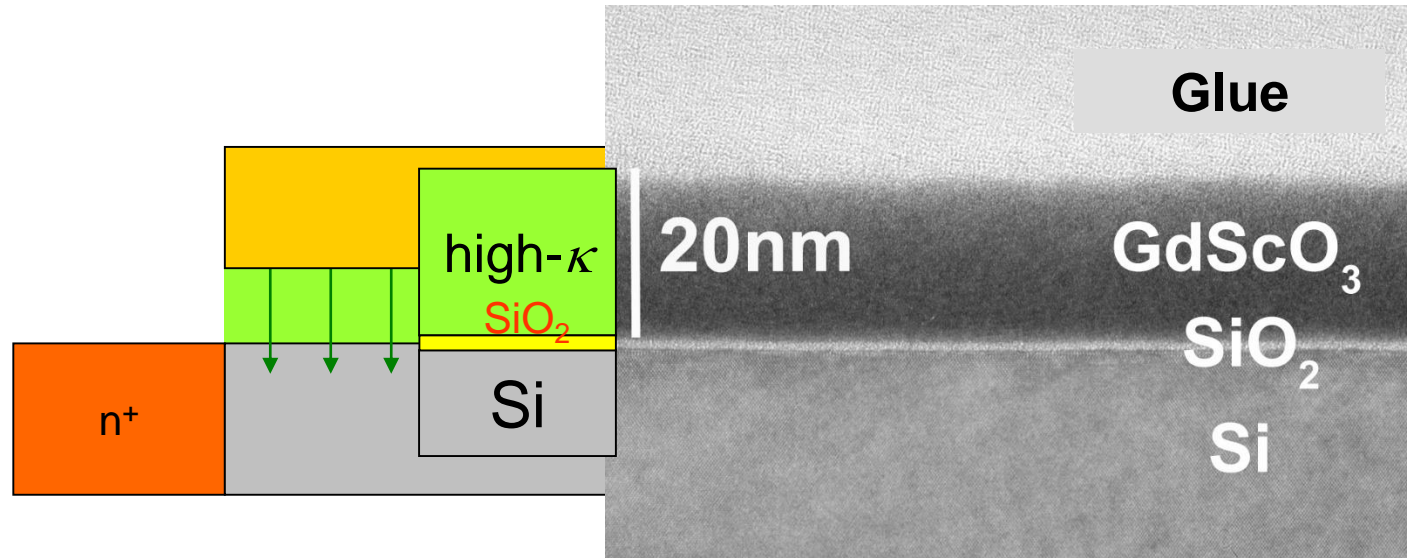
κ : rel. dielectric constant

E: electric field

J: tunneling/leakage current



„Parasitic“ interface

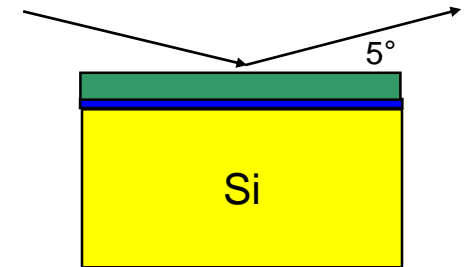
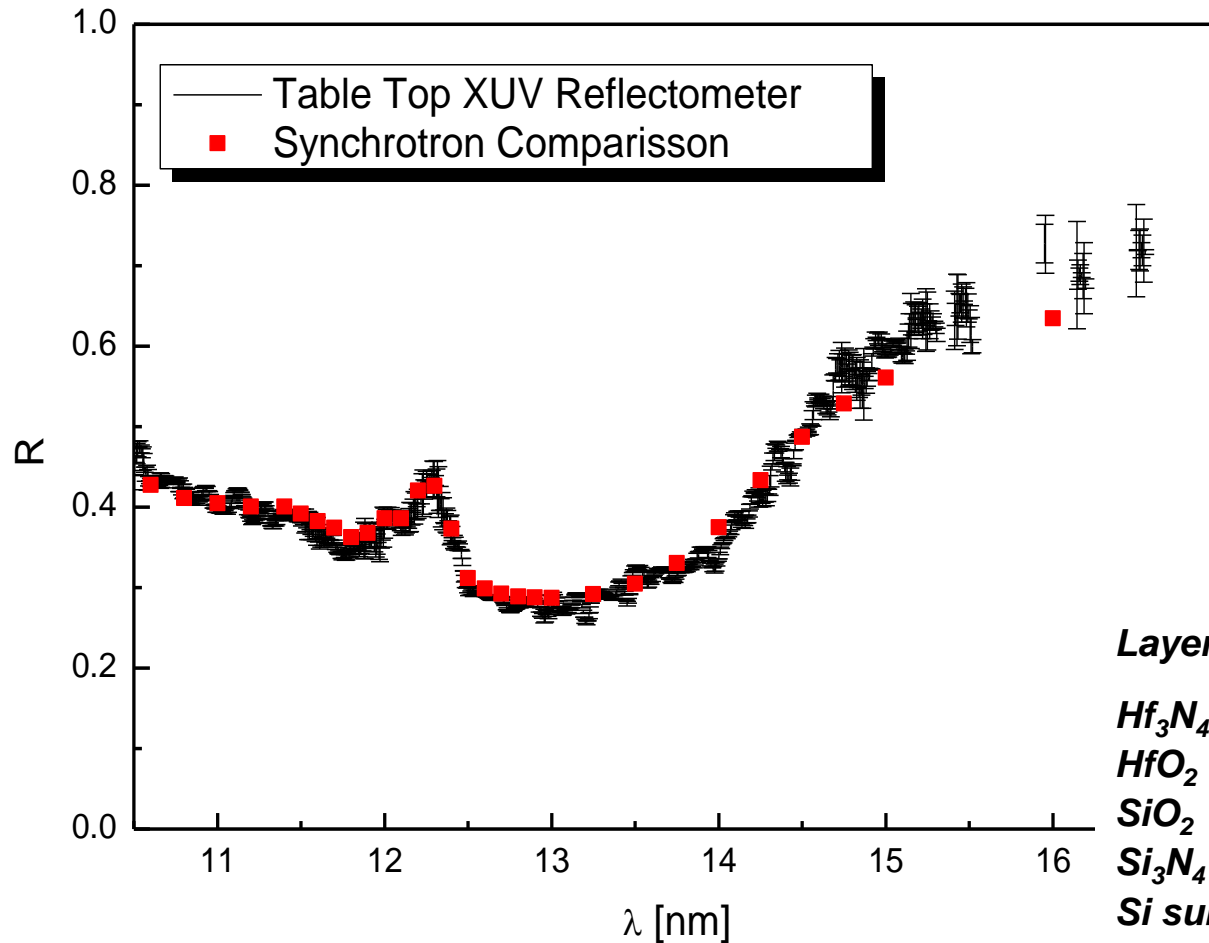


SiO_2 -Interface of high quality:

- decreases interface-states drastically
- increases charge carrier mobility in silicon
- decreases leakage current

Application example: characterization of high-k layers

Determination of ultra thin HfO_2 layers and buried oxide



Layer Model:

Hf_3N_4 d: 0.51 nm, density: 12.2 g/cm³

HfO_2 d: 0.97 nm, density: 9.4 g/cm³

SiO_2 d: 1.00 nm, density: 2.4 g/cm³

Si_3N_4 d: 0.83 nm, density: 4.1 g/cm³

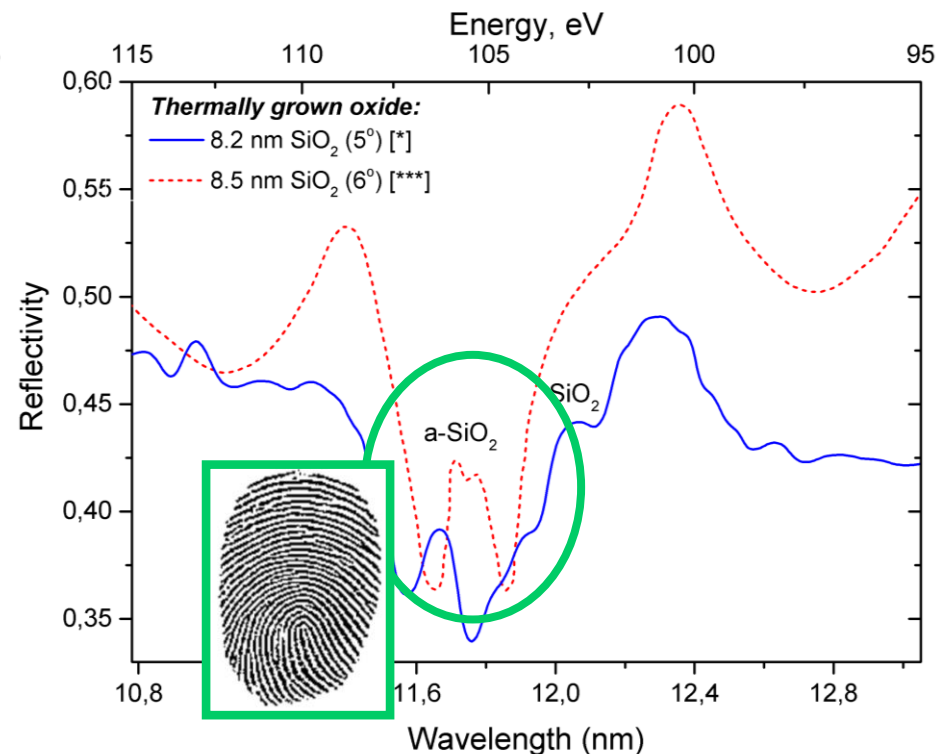
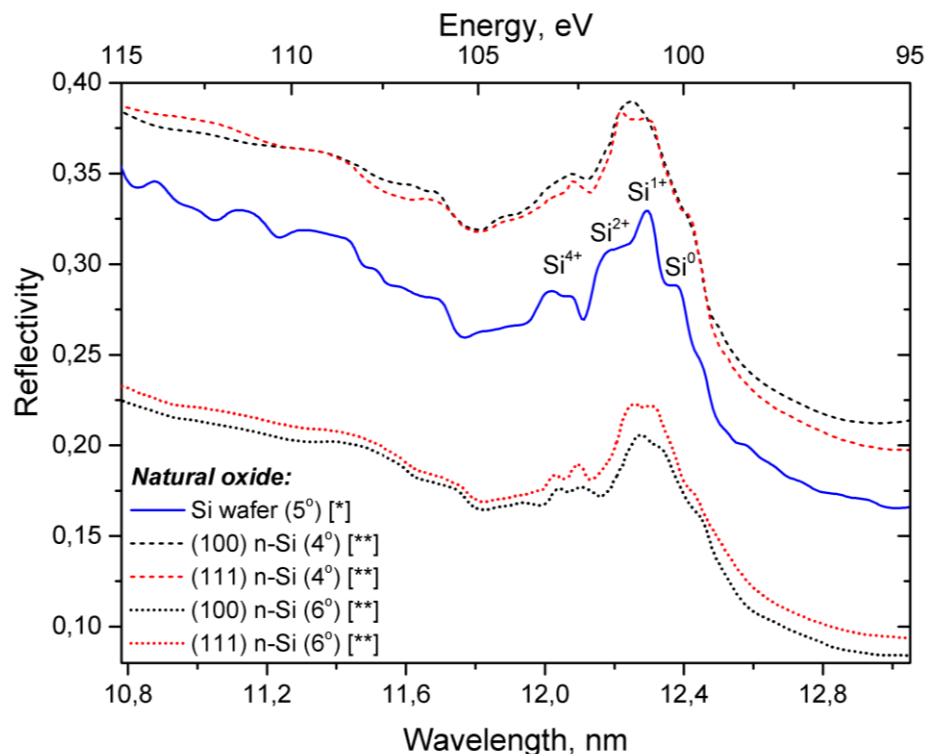
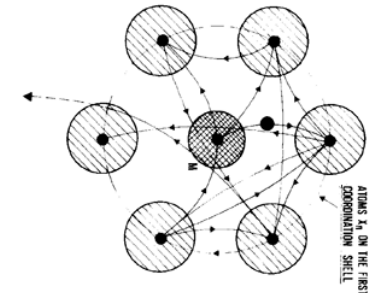
Si substrate

interlayer roughness/diffusion: 0.33 nm

Near-edge EUV reflectometry

Near-Edge X-Ray Absorption Fine Structure (NEXAFS)

- Determination of chemical bonds and local symmetry
- Quick qualitative interpretation (fingerprinting)



[*] M. Banyay, PhD thesis, RWTH Aachen (2011)

[**] E. O. Filatova, et al., Tech. Phys. Lett. **35** (1), 70-72 (2009)

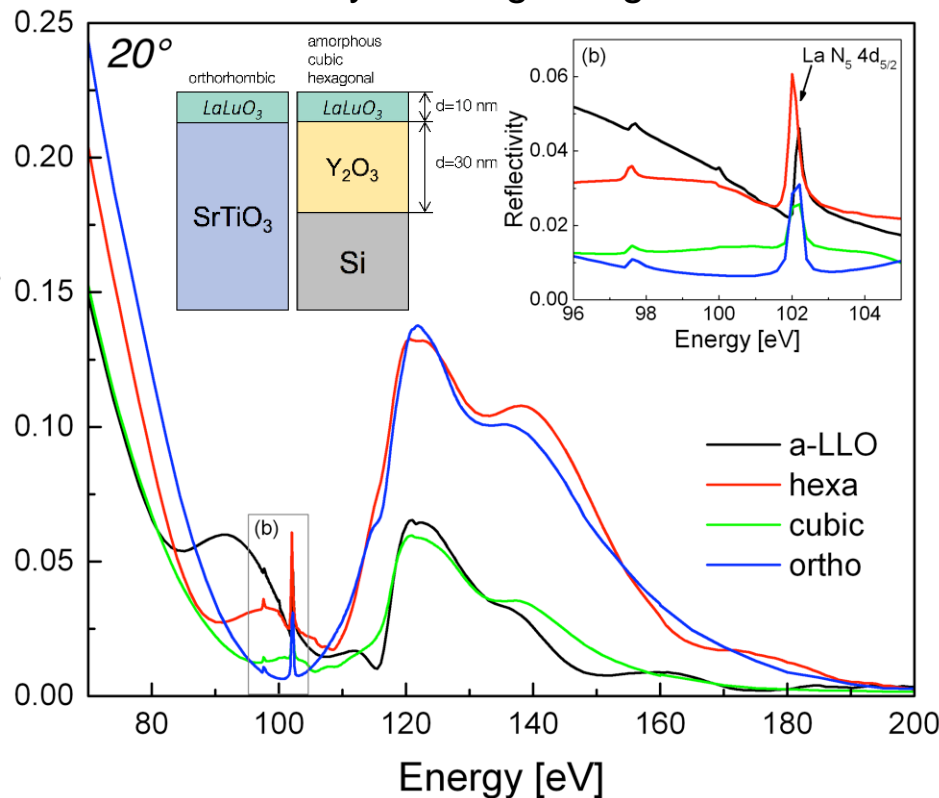
[***] E. O. Filatova, et al., Phys. Solid State **40** (7), 1237-1240 (1998)

**database built-up needed
(„fingerprint-concept“)**

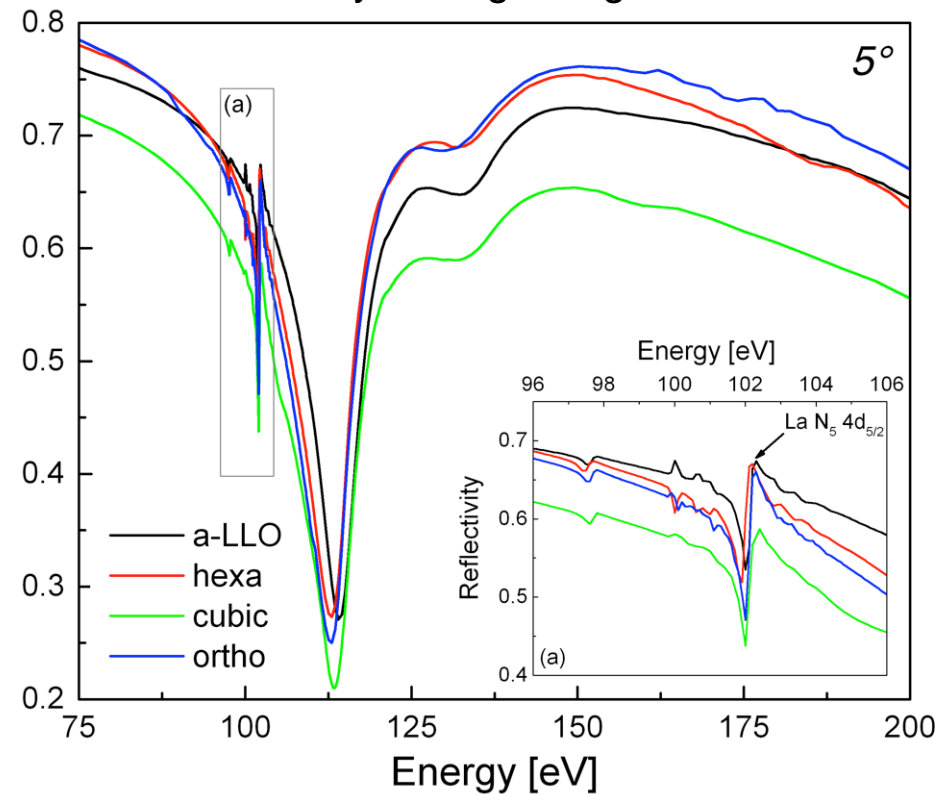
LaLuO₃ (LLO) layers of different crystallinity

- LLO – high-k material, promising as a gate dielectric (SiO₂, HfO₂ replacement)
- Four crystalline modifications of LLO have been investigated
- Untabulated near-edge features and La N-edge shift observed

Reflectivity at 20° grazing incidence



Reflectivity at 5° grazing incidence



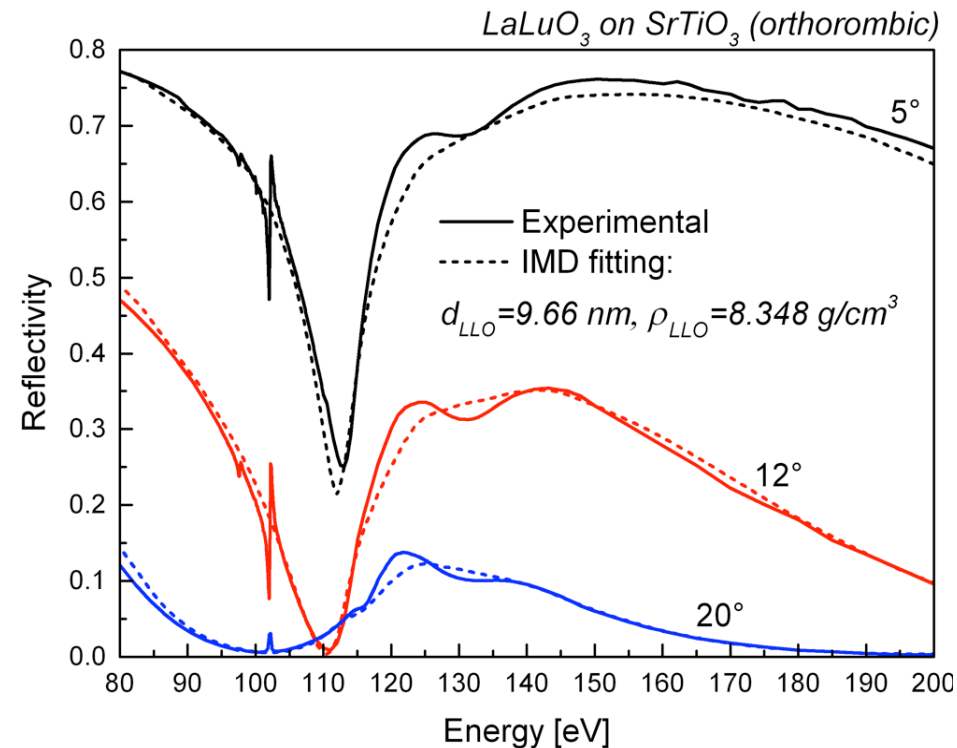
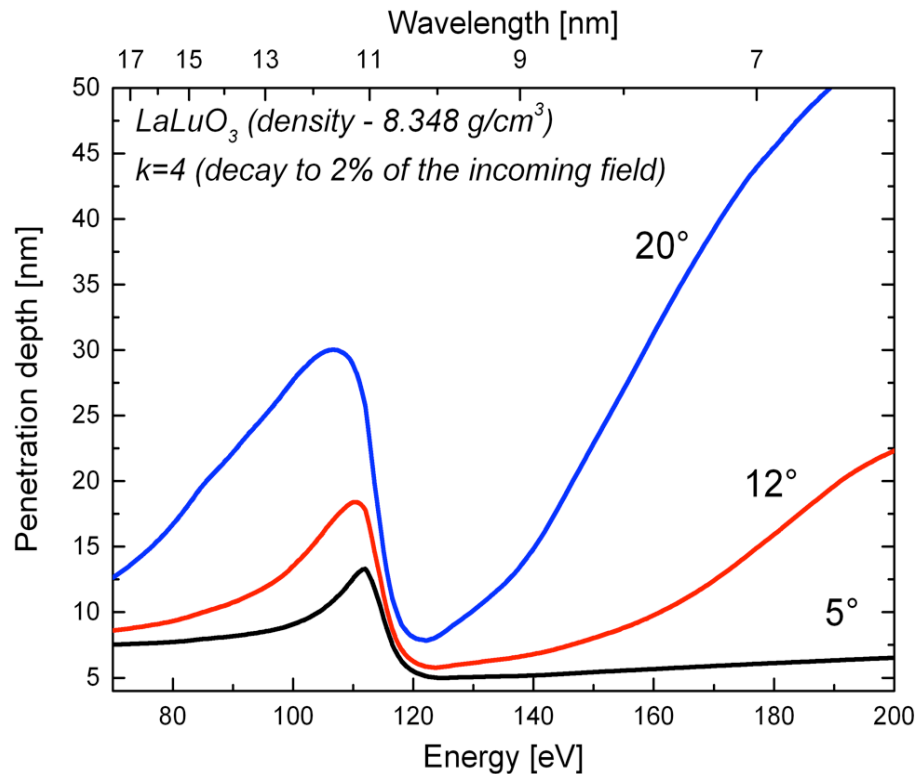
Reflectivity measurements from BEAR
beamline of ELETTRA synchrotron, Trieste

LaLuO₃ (LLO) layers of different crystallinity

Penetration depth of EUV radiation into the interface (angle-dependent):

$$z_0^2 = k \frac{\lambda^2}{8\pi^2 \beta^2} \left(\sqrt{(\theta^2 - 2\delta)^2 + 4\beta^2} + (\theta^2 - 2\delta) \right), \text{ where } n = 1 - \delta + i\beta$$

Penetration depth and fitting results

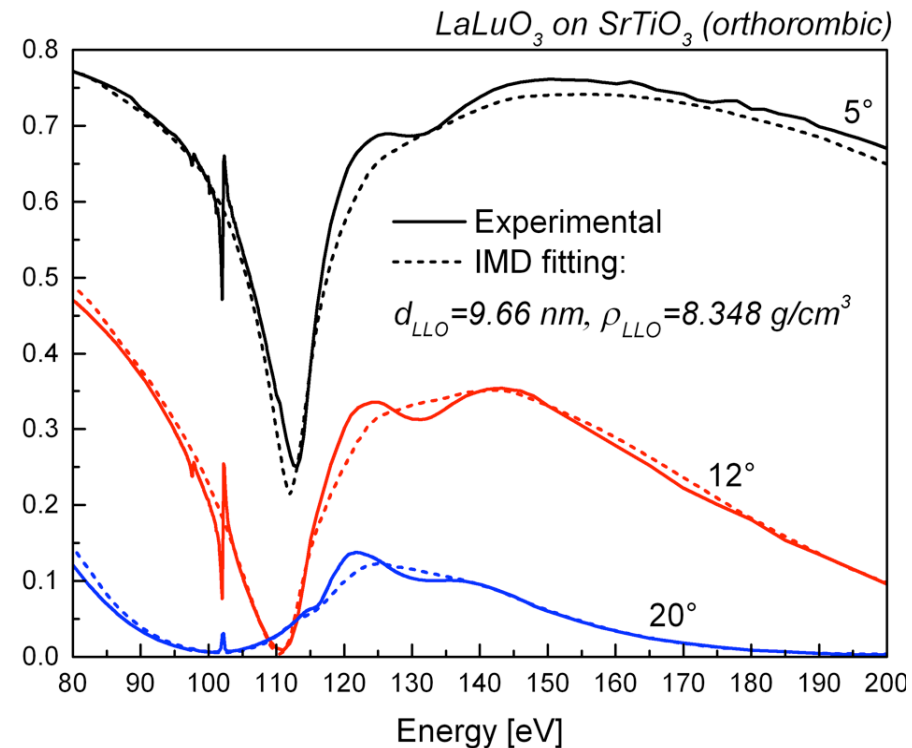
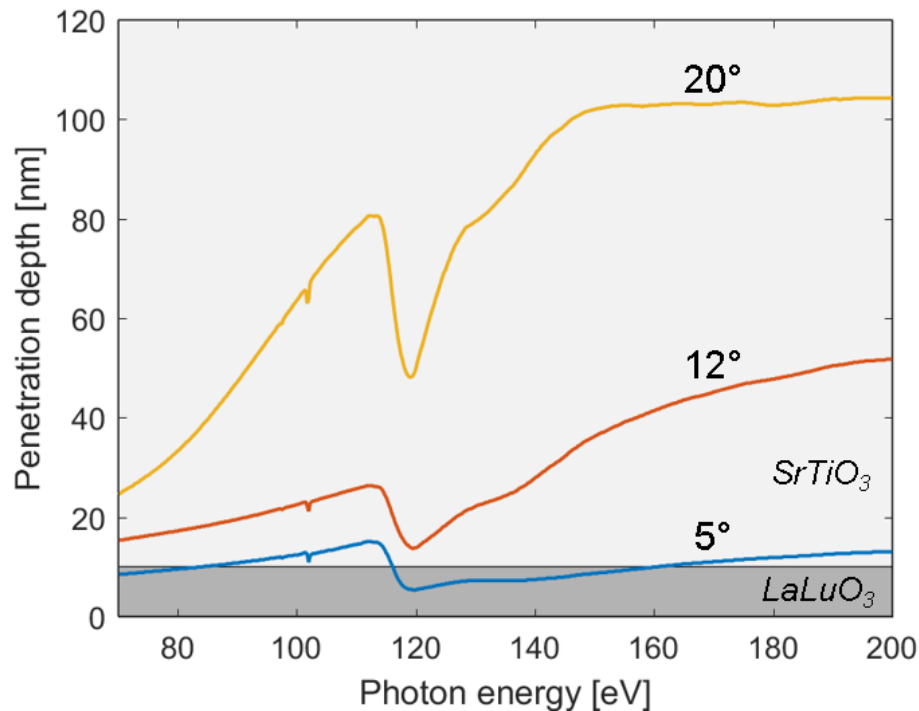


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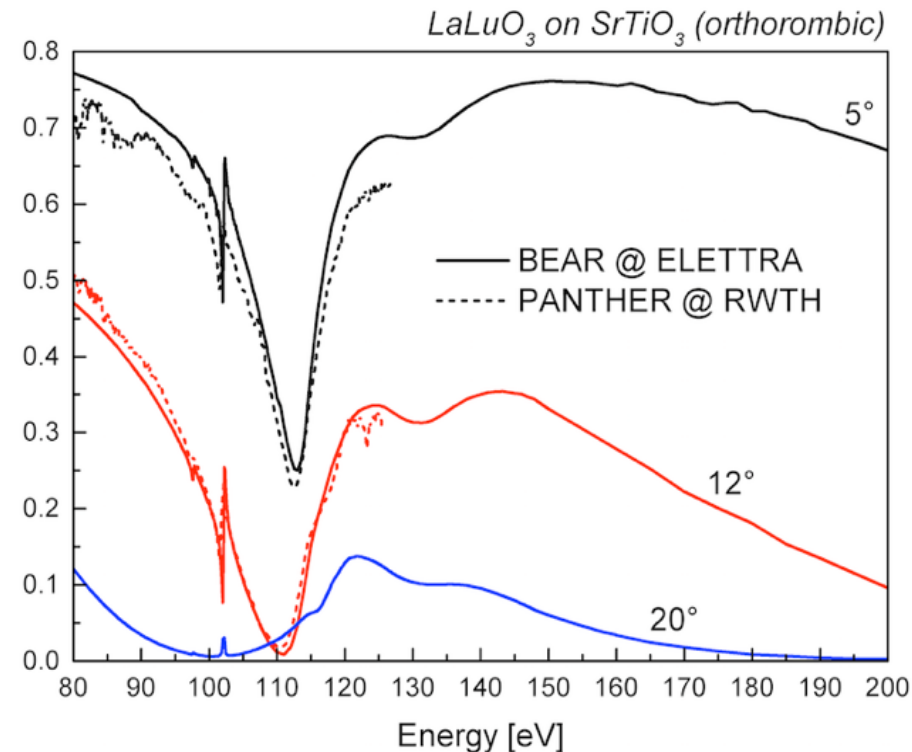
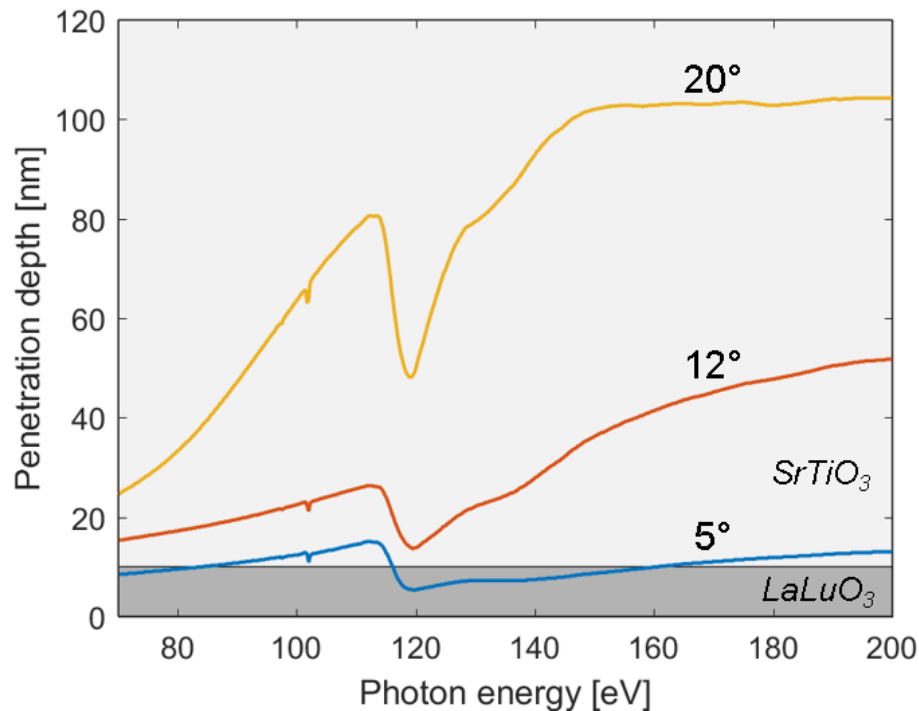


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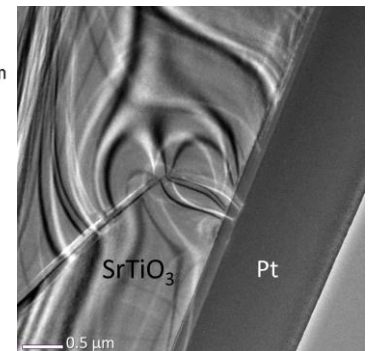
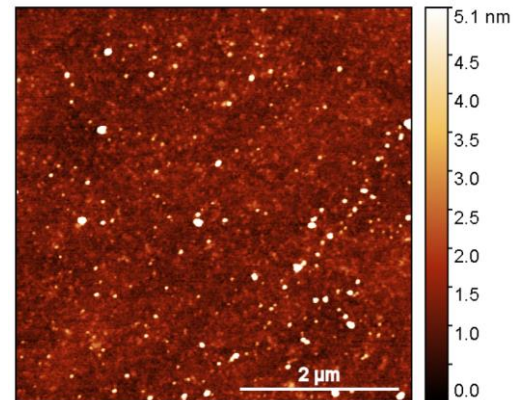
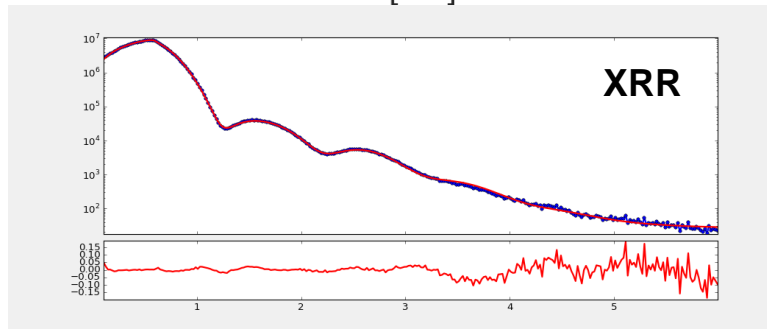
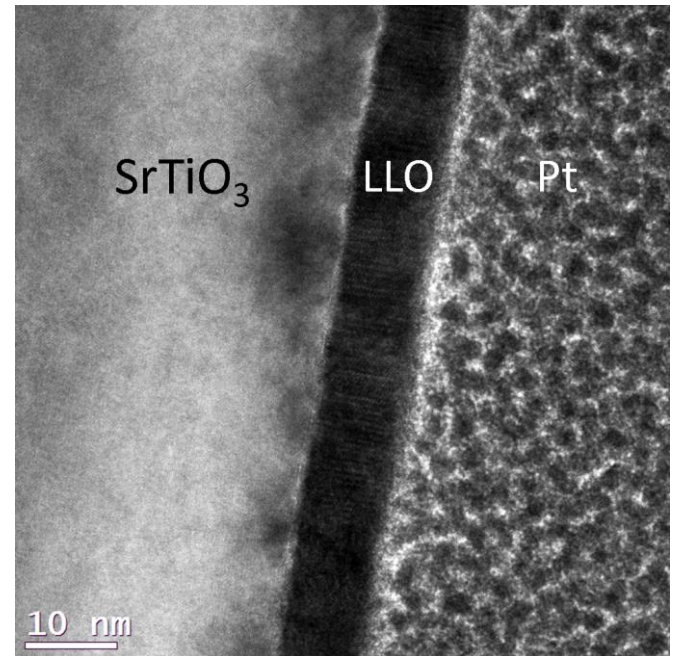
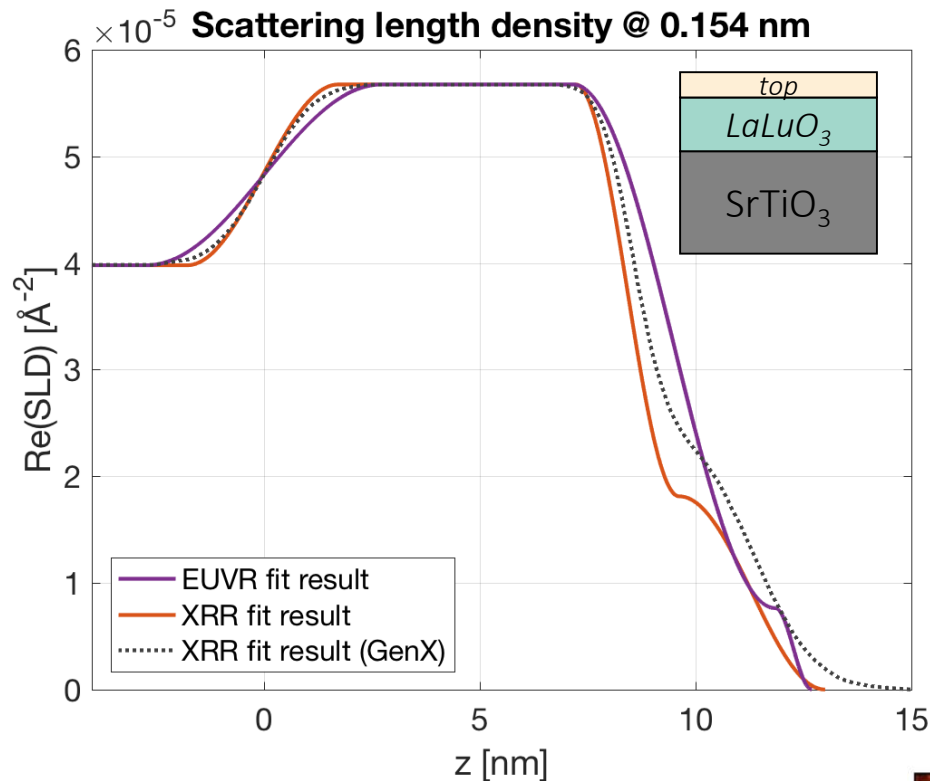
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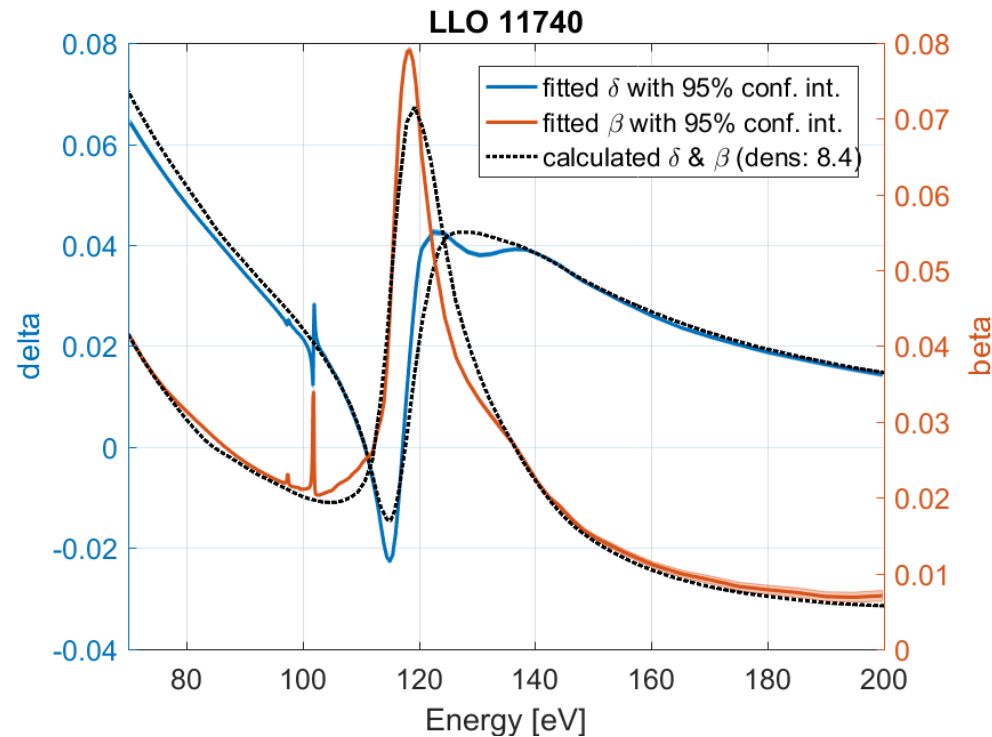
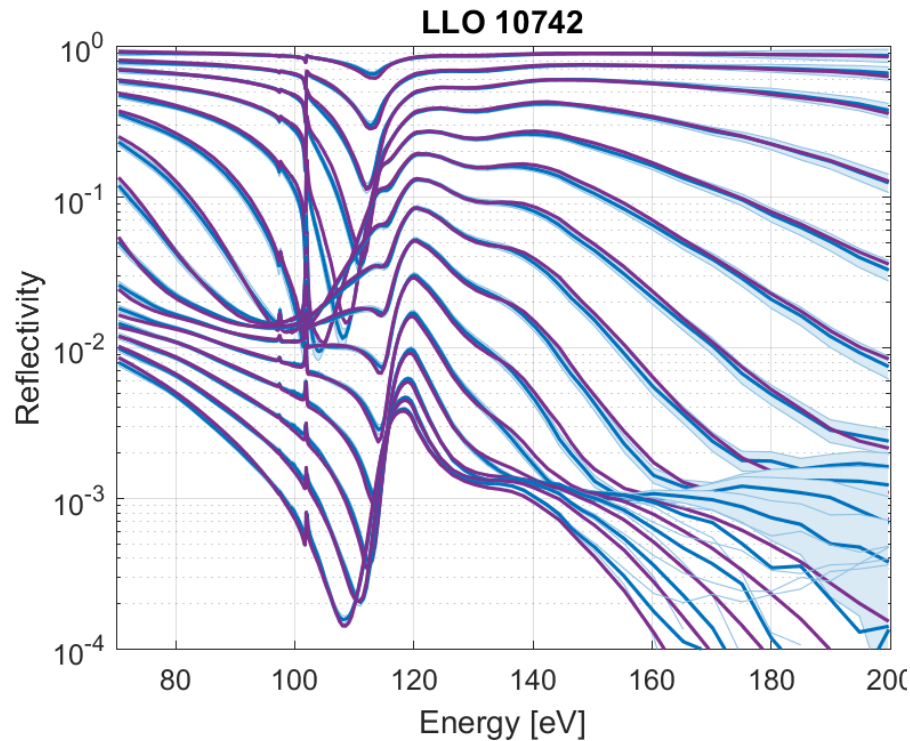
Penetration depth and fitting results



10 nm ortho-LLO #10742: SLD (δ) profiles, AFM / TEM images



Refractive index obtained from reflectance data: orthorhombic LLO



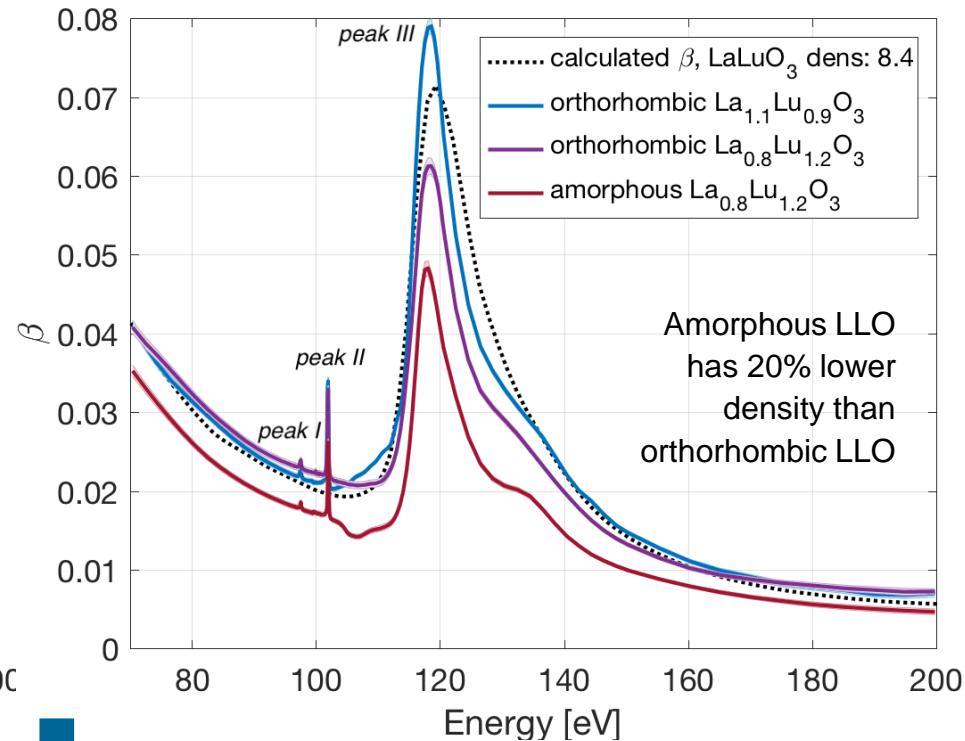
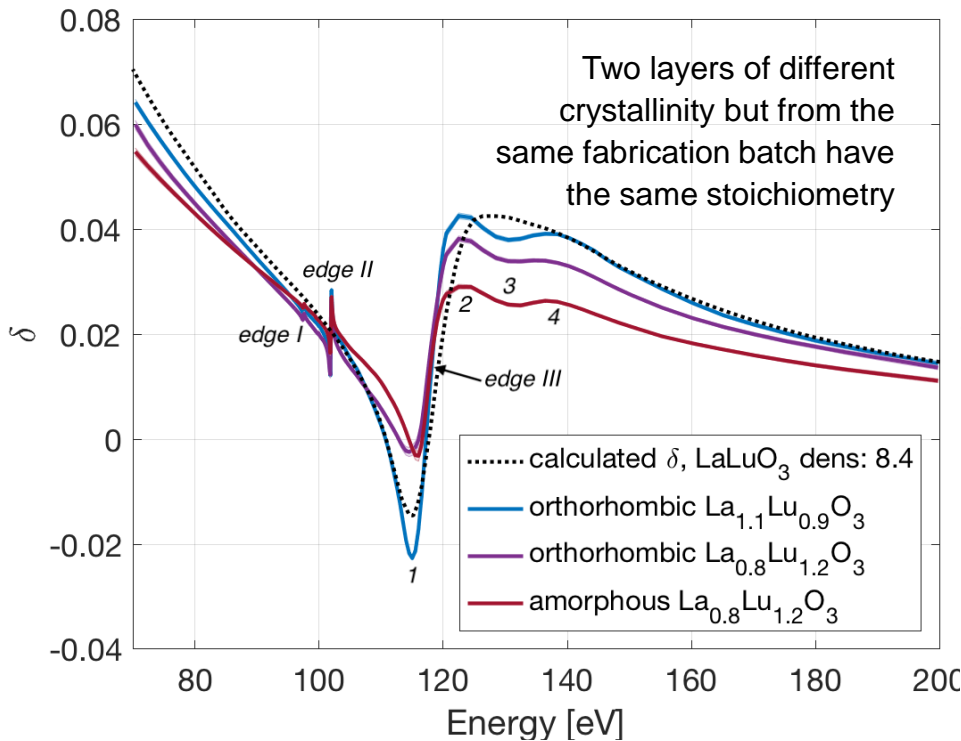
10 nm ortho-LLO #10742: EUV only fit / n&k + structure fit

STR.shape = 'cos'

thick	rough	dens	La	Lu	O	Sr	Ti	C
0	0.8520	0.8984	0	0	0	0	0	1.0
4.4434	4.6821	8.4000	1.0	1.0	3.0	0	0	0
0	5.4500	5.1200	0	0	3.0	1.0	1.0	0



Comparison of LLO optical constants



EUV reflectometry:

- Experimental determination of EUV optical constants of materials of interest
- Characteristic absorption edge features and near-edge oscillations
 - Amplitude directly connected to element content in compound
 - Determination of density and stoichiometry by comparing to calculations
- Responsive quality control method due to high sensitivity to chemical composition

Summary

- **EUV spectroscopic reflectometry is a powerful tool for analysis of thin films and film stacks with high surface/material sensitivity**
 - non-destructive analysis of ultra-thin films
 - strong element selectivity
 - determination of chemical bonds (NEXAFS)
 - surface sensitive technique (up to ~100 nm)
 - surface roughness determination
 - potential for sub- μm spatial resolution
 - simultaneous acquisition from one measurement
- **Laboratory EUV light for future metrology tools with high spatial resolution and throughput capability**
- **Pulse to pulse analysis allows to be independent on source fluctuations**
- **Multi-angle measurements allow to increase precision and stability**
 - experimental determination of EUV optical constants
 - determination of layer density and stoichiometry
- **Responsive quality control method due to high sensitivity to chemical composition and sample structure**

Thank you very much for your attention!

